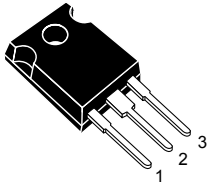
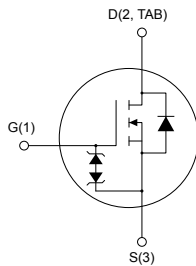


# N-channel 650 V, 51 mΩ typ., 48 A MDmesh DM6 Power MOSFET in a TO-247 package



TO-247



AM01475V1



## Features

Order code	$V_{DS}$	$R_{DS(on) \text{ max}}$	$I_D$
STW68N65DM6	650 V	59 mΩ	48 A

- Fast-recovery body diode
- Lower  $R_{DS(on)}$  per area vs previous generation
- Low gate charge, input capacitance and resistance
- 100% avalanche tested
- Extremely high dv/dt ruggedness
- Zener-protected

## Applications

- Switching applications

## Description

This high-voltage N-channel Power MOSFET is part of the MDmesh DM6 fast-recovery diode series. Compared with the previous MDmesh fast generation, DM6 combines very low recovery charge ( $Q_{rr}$ ), recovery time ( $t_{rr}$ ) and excellent improvement in  $R_{DS(on)}$  per area with one of the most effective switching behaviors available in the market for the most demanding high-efficiency bridge topologies and ZVS phase-shift converters.

### Product status links

[STW68N65DM6](#)

### Product summary

<b>Order code</b>	STW68N65DM6
<b>Marking</b>	68N65DM6
<b>Package</b>	TO-247
<b>Packing</b>	Tube

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	48	A
$I_D$	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	30	A
$I_D^{(1)}$	Drain current (pulsed)	172	A
$P_{TOT}$	Total power dissipation at $T_C = 25\text{ }^\circ\text{C}$	330	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	100	V/ns
$di/dt^{(2)}$	Peak diode recovery current slope	1000	A/ $\mu\text{s}$
$dv/dt^{(3)}$	MOSFET $dv/dt$ ruggedness	100	V/ns
$T_{STG}$	Storage temperature range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating junction temperature range		$^\circ\text{C}$

1. Pulse width limited by safe operating area.
2.  $I_{SD} \leq 48\text{ A}$ ,  $V_{DS}(\text{peak}) < V_{(BR)DSS}$ ,  $V_{DD} = 400\text{ V}$ .
3.  $V_{DS} \leq 520\text{ V}$ .

**Table 2. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	0.38	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	50	$^\circ\text{C/W}$

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}$	Avalanche current, repetitive or not repetitive ( $t_p$ limited by $T_J$ max)	9	A
$E_{AS}$	Single pulse avalanche energy (starting $T_J = 25\text{ }^\circ\text{C}$ , $I_D = I_{AR}$ ; $V_{DD} = 50\text{ V}$ )	930	mJ

## 2 Electrical characteristics

$T_C = 25\text{ °C}$  unless otherwise specified

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	650			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{ V}, V_{DS} = 650\text{ V}$			10	$\mu\text{A}$
		$V_{GS} = 0\text{ V}, V_{DS} = 650\text{ V}, T_C = 125\text{ °C}^{(1)}$			100	
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0\text{ V}, V_{GS} = \pm 25\text{ V}$			$\pm 5$	$\mu\text{A}$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	3.25	4	4.75	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}, I_D = 24\text{ A}$		51	59	m $\Omega$

1. Defined by design, not subject to production test.

**Table 5. Dynamic characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100\text{ V}, f = 1\text{ MHz}, V_{GS} = 0\text{ V}$	-	3528	-	$\text{pF}$
$C_{oss}$	Output capacitance		-	258	-	
$C_{rss}$	Reverse transfer capacitance		-	1.5	-	
$C_{oss\text{ eq}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0\text{ to }520\text{ V}, V_{GS} = 0\text{ V}$	-	609	-	
$R_G$	Intrinsic gate resistance	$f = 1\text{ MHz}, I_D = 0\text{ A}$	-	1.25	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 520\text{ V}, I_D = 48\text{ A}, V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 14. Test circuit for gate charge behavior)	-	80	-	nC
$Q_{gs}$	Gate-source charge		-	21.5	-	
$Q_{gd}$	Gate-drain charge		-	35	-	

1.  $C_{oss\text{ eq}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 325\text{ V}, I_D = 34\text{ A},$ $R_G = 4.7\text{ }\Omega, V_{GS} = 10\text{ V}$	-	25	-	ns
$t_r$	Rise time		-	32	-	ns
$t_{d(off)}$	Turn-off delay time	(see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	76	-	ns
$t_f$	Fall time		-	9	-	ns

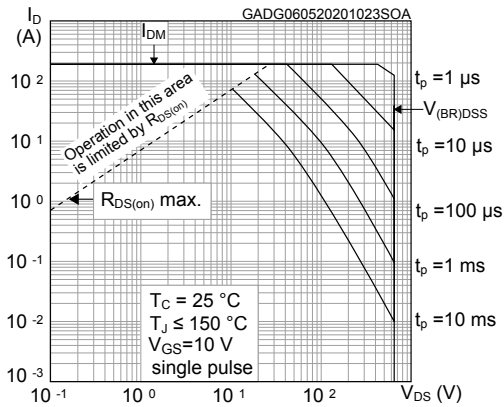
**Table 7. Source-drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		48	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		172	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0\text{ V}$ , $I_{SD} = 48\text{ A}$	-		0.98	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 48\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_{DD} = 60\text{ V}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	135		ns
$Q_{rr}$	Reverse recovery charge		-	0.641		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	9.5		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 48\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $V_{DD} = 60\text{ V}$ , $T_J = 150\text{ }^\circ\text{C}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	245		ns
$Q_{rr}$	Reverse recovery charge		-	2.45		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	20		A

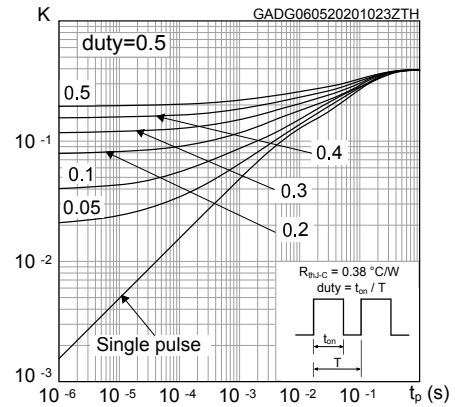
1. Pulse width is limited by safe operating area.
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

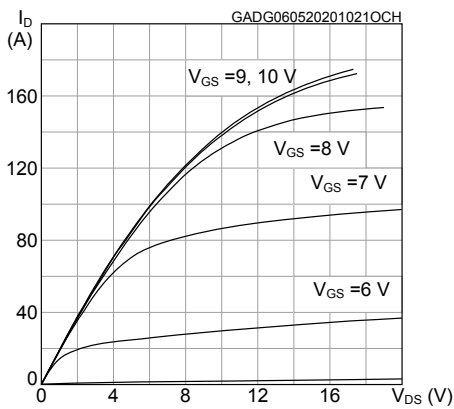
**Figure 1. Safe operating area**



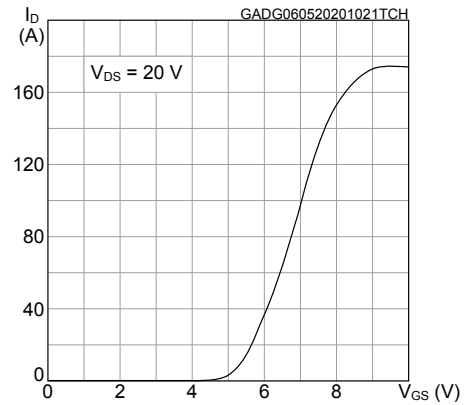
**Figure 2. Maximum transient thermal impedance**



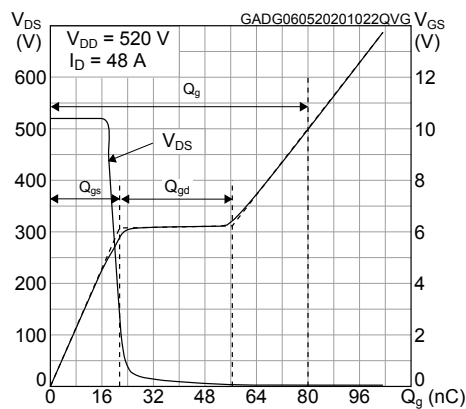
**Figure 3. Typical output characteristics**



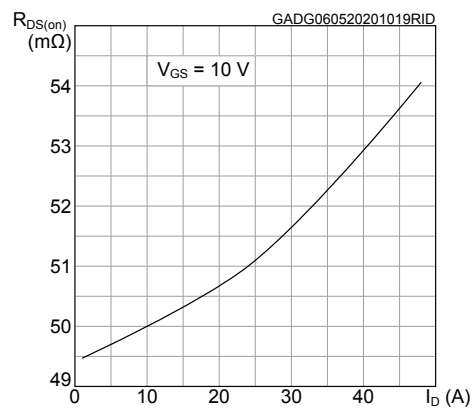
**Figure 4. Typical transfer characteristics**



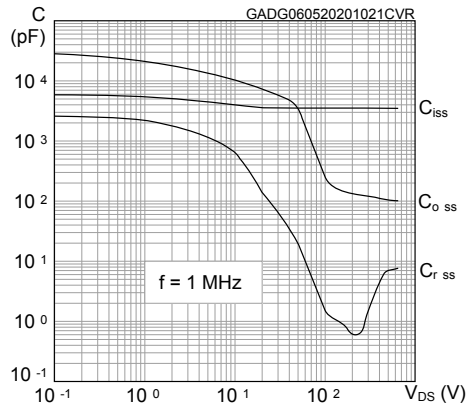
**Figure 5. Typical gate charge characteristics**



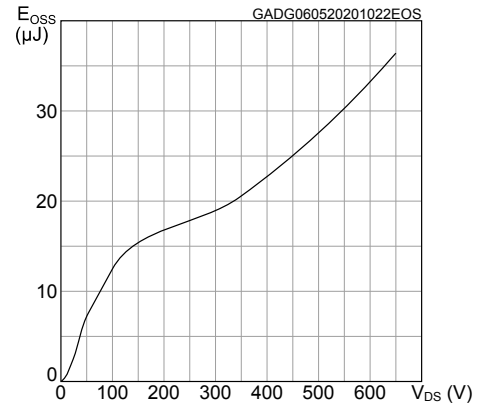
**Figure 6. Typical drain-source on-resistance**



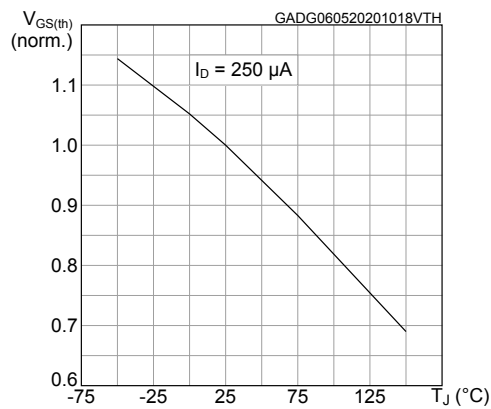
**Figure 7. Typical capacitance characteristics**



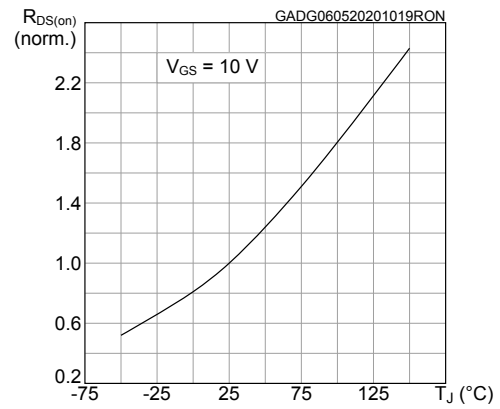
**Figure 8. Typical output capacitance stored energy**



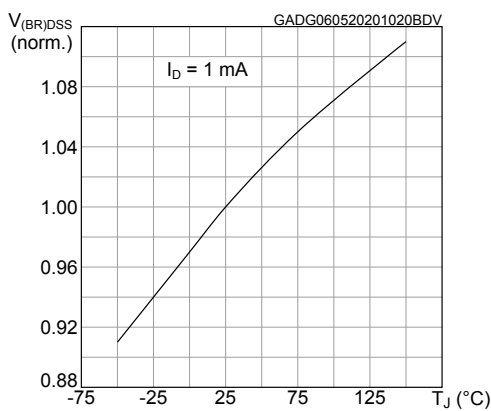
**Figure 9. Normalized gate threshold vs temperature**



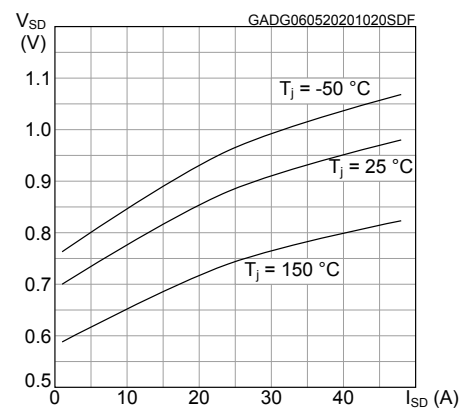
**Figure 10. Normalized on-resistance vs. temperature**



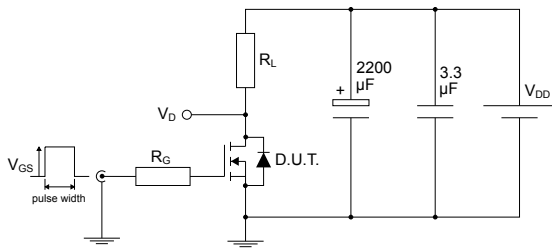
**Figure 11. Normalized breakdown voltage vs temperature**



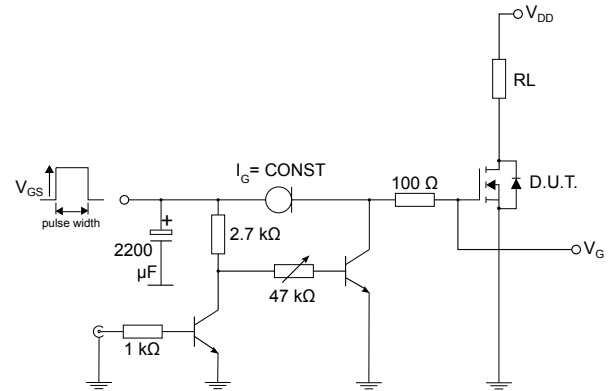
**Figure 12. Typical reverse diode forward characteristics**



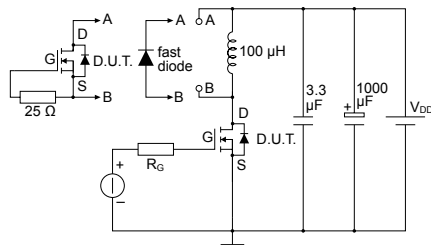
### 3 Test circuits

**Figure 13. Test circuit for resistive load switching times**


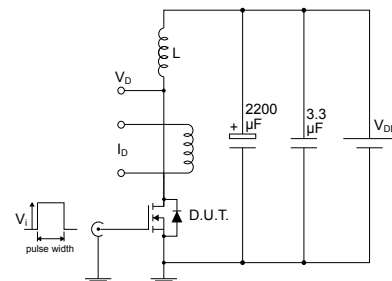
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**Figure 14. Test circuit for gate charge behavior**


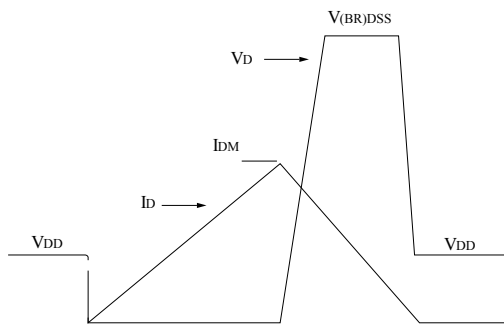
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**Figure 15. Test circuit for inductive load switching and diode recovery times**


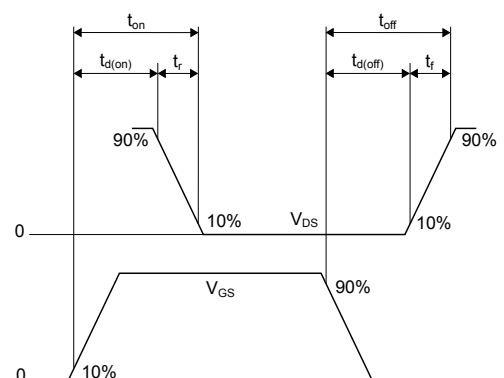
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**Figure 16. Unclamped inductive load test circuit**


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**Figure 17. Unclamped inductive waveform**


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**Figure 18. Switching time waveform**


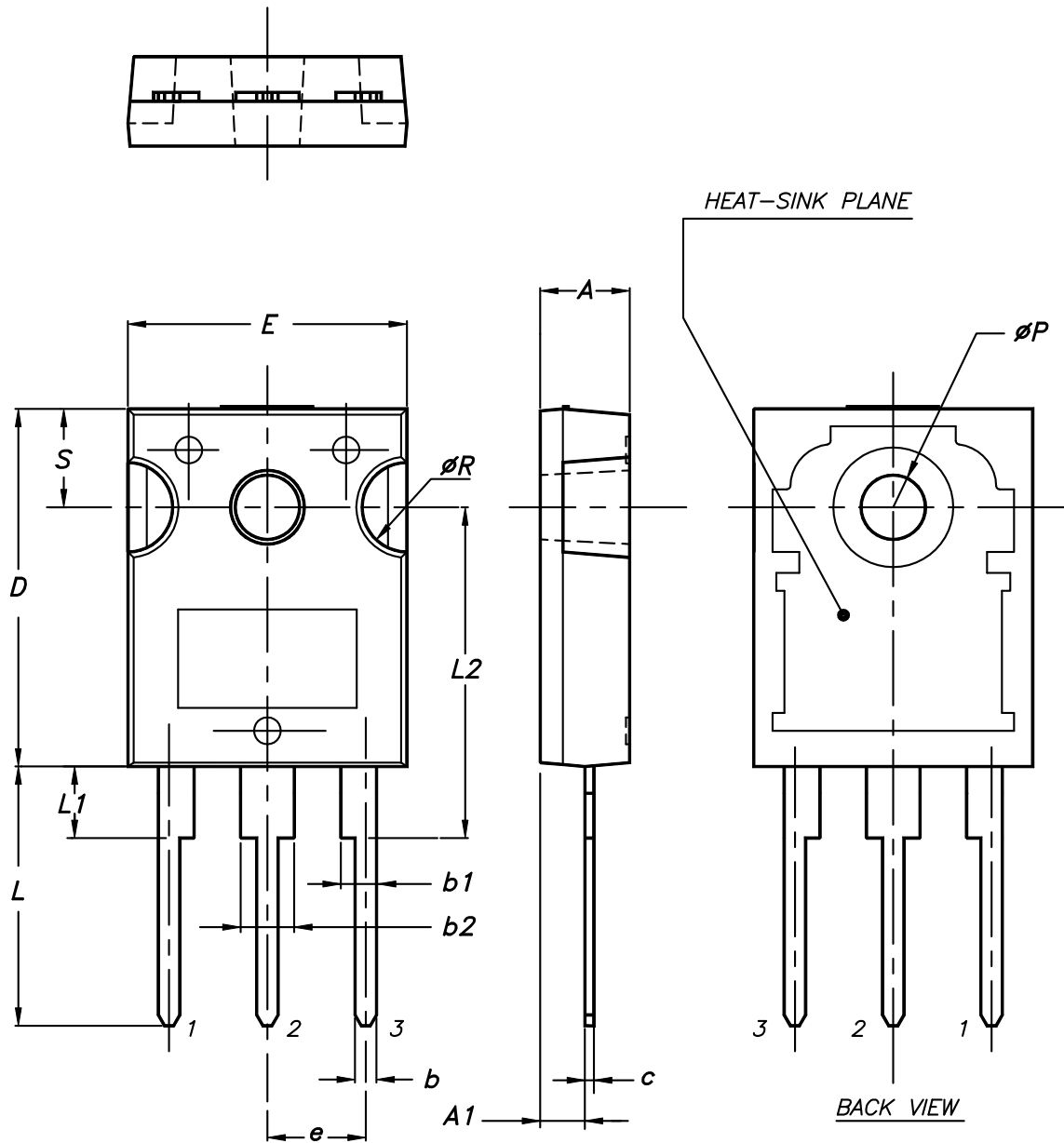
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## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 TO-247 package information

Figure 19. TO-247 package outline



0075325\_9



**Table 8. TO-247 package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

## Revision history

**Table 9. Document revision history**

Date	Version	Changes
08-May-2020	1	First release. Part number previously included in datasheet DS12367.

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